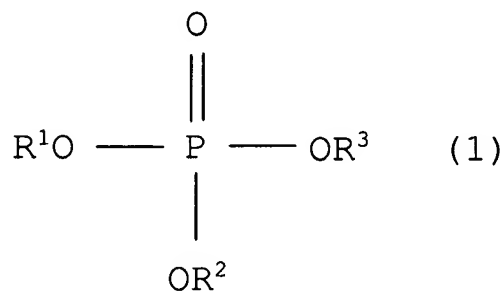


AMENDMENTS TO THE CLAIMS

1. (Currently amended) ~~An~~A dielectric inorganic powder-containing resin composition comprising inorganic powder, a binder resin, and a phosphorus compound represented by formula (1):



wherein R^1 , R^2 and R^3 independently represent H, an alkyl group, an alkylaryl group, NH_4^+ (ammonium) or $-(\text{CH}_2\text{CH}_2\text{O})_n-\text{R}^4$, wherein n is 1 to 15, and R^4 represents H, an alkyl group, an alkylaryl group or a (meth)acryloyl group, and

wherein the binder resin is (meth)acrylic resin,

wherein the (meth)acrylic resin has a carboxyl group and has an acid value of 0.5 to 5 KOH mg/g.

2. (Original) The inorganic powder-containing resin composition according to claim 1, wherein the weight-average molecular weight of the binder resin is 50,000 to 500,000.

3. (Canceled)

4. (Canceled)

5. (Canceled)

6. (Previously presented) The inorganic powder-containing resin composition according to claim 1, wherein 5 to 50 parts by weight of the binder resin and 0.1 to 10 parts by weight of the phosphorus compound relative to 100 parts by weight of the inorganic powder are contained.

7. (Previously presented) The inorganic powder-containing resin composition according to claim 1, wherein the inorganic powder is glass powder.

8. (Previously presented) The inorganic powder-containing resin composition according to claim 1, wherein the viscosity of the inorganic powder at 600°C is 150 Pa·s or less.

9. (Canceled)

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10. (Previously presented) A film-forming material layer comprising the inorganic powder-containing resin composition according to claim 1 formed in a sheet form.

11. (Original) A transfer sheet comprising at least the film-forming material layer according to claim 10 laminated on a support film.

12. (Withdrawn) A dielectric layer comprising the film-forming material layer according to claim 10 sintered therein.

13. (Withdrawn) A method of producing a substrate having a dielectric layer formed thereon, comprising the step of transferring the film-forming material layer of the transfer sheet according to claim 11 onto a substrate and the step of sintering the transferred film-forming material layer at 550 to 650°C to form a dielectric layer on the substrate.

14. (Withdrawn) A substrate having a dielectric layer formed thereon, which is produced according to the method of claim 13.

15. (Canceled)

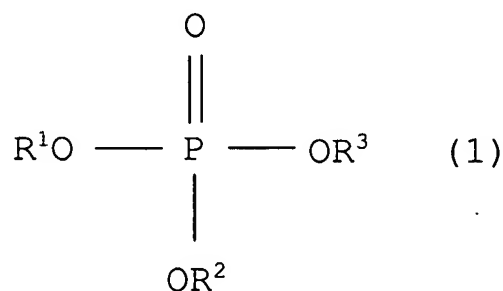
16. (Previously presented) The inorganic powder-containing resin composition according to claim 17, wherein at least one of R¹, R² and R³ is H.

17. (Currently amended) ~~An~~ A dielectric inorganic powder-containing resin composition which is sinterable and comprises:

100 parts by weight of inorganic powder;

5 to 50 parts by weight of a binder resin; and

0.1 to 10 parts by weight of a phosphorus compound represented by formula (1):



wherein R¹, R² and R³ independently represent H, an alkyl group, an alkylaryl group, ~~NH₄⁺ (ammonium)~~ or -(CH₂CH₂O)_n-R⁴, wherein n is 1 to 15, and R⁴ represents H, an alkyl group, an alkylaryl group or a (meth)acryloyl group, and wherein the binder

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resin is a (meth)acrylic resin having a carboxyl group and has an acid value of 0.5 to 5 KOH mg/g.

18. (Previously presented) The inorganic powder-containing resin composition according to claim 17, wherein the inorganic powder has a softening point of 400 to 650°C.

19. (New) The film-forming material layer according to claim 10, wherein the layer has a thickness of 30 to 100 μm .